

Academia meets Industry

On

Advanced interconnections for chip packaging in future detectors

Organizing Committee:

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8th-9th April 2013
LNF

With the assistance of:



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- Among the best experts from Industry and Academia
- Succeeded in attracting 80 participants
- Dense programme
 - Opportunity of networking at coffee breaks and fingerfood dinner
 - Companies to present their products at coffee breaks as well
- Agenda Monday
 - Needs from communities → Convener: Laurent Serin, IN2P3
 - TSV-based vertical interconnections → Convener: Abdenour Lounis, Uni Paris Sud
 - TSV → Convener: H.G. Moser (MPI)
- Networking Finger Food Dinner
- Agenda Tuesday
 - **9:15** Integration of sensors with 3D electronics → Convener: Valerio Re, INFN
 - Chip-stacking through microbump bonding → Convener: Michael Campbell, CERN
 - Frontiers in interconnections → Convener: Michael Campbell, CERN
 - Event Summary and roadmap for collaborative R&D
- Lunch → Possibility of networking after the event

The organisation committee wishes you a very fruitful event!